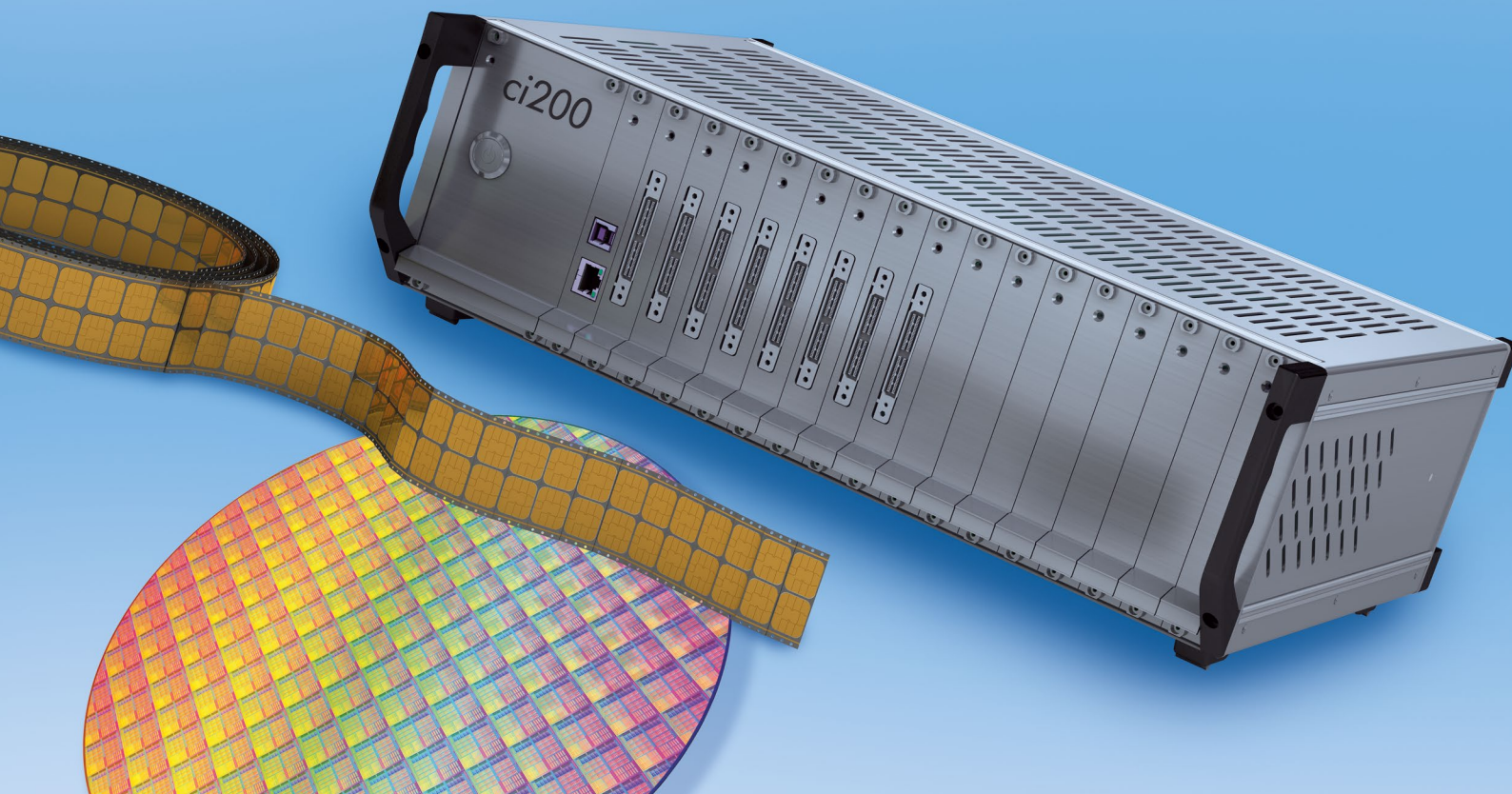


ci200 - High Speed

Production ATE for final & wafer test



- Electrical parameter test
- Simplified test program generation
- Smart Card & RFID/NFC complete protocol test
- Up to 32 DUTs in parallel
- Full parallel execution for fastest test time
- Accurate VNA for impedance measurement

ci200

Reliable & Integrated Production ATE

General Description

The ci200 production test system satisfies all Smart Card and RFID/NFC final or wafer test requirements in a fully integrated solution. It offers electrical parameters, impedance, protocol and memory tests, allowing up to 32 fully parallel DUTs.

Derived from our proven certification test tool, the ci200 introduces the best-in-class test coverage and precision at the fastest possible test time.

Engineered for reliability and performance, the ci200 offers accuracy and scalability for semiconductor manufacturing. It enables manufacturers to accelerate testing, optimize efficiency, and significantly reduce cost per die.



Applications

- General Purpose Semiconductor tester for Analog, Digital, Mixed Signal and RF test
- Final and Wafer test
- NFC & Smartcard chip/module test
- Device personalization and memory programming

Full protocol coverage

- ISO 7816
- ISO 14443
- ISO 15693
- ISO 18092
- ISO 11785
- SPI, I2C
- EMVCo
- NFC Forum

Key benefits

- Fastest possible test speed
- Full parallel execution on up to 32 DUTs
- High precision electrical parametric measurements (integrated VNA)
- Full coverage of supported protocol verified against certified tools
- Simplified test program generation via set of flexible API
- Industrial Robustness with easy maintenance



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